This applies in particular to encapsulated or potted transformers and/or coils that are not mounted flush to the board.

Acceptable – Class 1,2,3

- Bonding requirements should be specified in engineering documents, but as a minimum, components are bonded to mounting surface in at least 4 places evenly spaced around component when no mechanical support is used, see Figure 7-62-A.
- At least 20% of the total periphery of the component is bonded, see Figure 7-62-B.
- Bonding material firmly adheres to both the bottom and sides of the component and to the printed wiring board, see Figure 7-62-C.
- Adhesive material does not interfere with formation of required solder connection.

Defect – Class 1,2,3

- Bonding requirements are less than specified.
- Any bonding spots failing to wet and show evidence of adhesion to both the bottom and side of the component and the mounting surface, see Figure 7-63-B.
- Less than 20% of the total periphery of the component is bonded, see Figure 7-63-C.
- The bonding material forms too thin a column to provide good support, see Figure 7-63-D.
- Adhesive material interferes with formation of required solder connection.
This applies in particular to encapsulated or potted transformers and/or coils that are not mounted flush to the board.

### Acceptable - Class 1,2,3
- Bonding requirements should be specified in engineering documents, but as a minimum, components are bonded to mounting surface in at least four places evenly spaced around component when no mechanical support is used, see Figure 7-63-A.
- At least 20% of the total periphery of the component is bonded, see Figure 7-63-B.
- Bonding material firmly adheres to both the bottom and sides of the component and to the printed wiring board, see Figure 7-63-C.
- Adhesive material does not interfere with formation of required solder connection.

### Defect - Class 1,2,3
- Bonding requirements are less than the specified requirements.
- Any bonding spots failing to wet and show evidence of adhesion to both the bottom and side of the component and the mounting surface, see Figure 7-64-B.
- Less than 20% of the total periphery of the component is bonded, see Figure 7-64-C.
- The bonding material forms too thin a column to provide good support, see Figure 7-64-D.
- Adhesive material interferes with formation of required solder connection.
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7.2.3 Component Securing – Other Devices

Acceptable – Class 1, 2, 3
- Component is held firmly against the mounting surface.
- There is no damage to the component body or insulation from the securing device.
- Conductive securing device does not violate minimum electrical clearance.

Defect – Class 1, 2, 3
- Component body damaged from securing device.
- Conductive securing device violates minimum electrical clearance.
7.2.3 Component Securing - Other Devices

Acceptable - Class 1,2,3
- Component is held firmly against the mounting surface.
- There is no damage to the component body or insulation from the securing device.
- Conductive securing device does not violate minimum electrical clearance.

Figure 7-65
Target – Class 1,2,3
- The entire body length of the component is in contact with the board surface.
- Components required to be mounted off the board are at least 1.5 mm [0.06 in] from the board surface; e.g., high heat dissipating.

Figure 7-66
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7.3 Supported Holes

7.3.1 Supported Holes - Axial Leaded - Horizontal

Target - Class 1,2,3
- The entire body length of the component is in contact with the board surface.
- Components required to be mounted off the board are at least 1.5 mm [0.06 in] from the board surface, e.g., high heat dissipating.